PD-96990A

International Rectifier

RADIATION HARDENED POWER MOSFET SURFACE MOUNT (SMD-2)

2N7585U2
IRHNA67264
250V, N-CHANNEL
R6 TECHNOLOGY

Product Summary

Part Number	Radiation Level	$R_{DS(on)}$	I_D
IRHNA67264	100K Rads (Si)	0.040Ω	50A
IRHNA63264	300K Rads (Si)	0.040Ω	50A

SMD-2

International Rectifier's R6™ technology provides superior power MOSFETs for space applications. These devices have improved immunity to Single Event Effect (SEE) and have been characterized for useful performance with Linear Energy Transfer (LET) up to 90MeV/(mg/cm²). Their combination of very low $R_{DS(on)}$ and faster switching times reduces power loss and increases power density in today's high speed switching applications such as DC-DC converters and motor controllers. These devices retain all of the well established advantages of MOSFETs such as voltage control, ease of paralleling and temperature stability of electrical parameters.

Features:

- Low $R_{DS(on)}$
- Fast Switching
- Single Event Effect (SEE) Hardened
- Low Total Gate Charge
- Simple Drive Requirements
- Ease of Paralleling
- Hermetically Sealed
- Surface Mount
- Ceramic Package
- Light Weight

Absolute Maximum Ratings — Pre-Irradiation

	Parameter		Units
I_D @V_{GS} = 12V,T_C = 25°C	Continuous Drain Current	50	A
I_D @V_{GS} = 12V,T_C = 100°C	Continuous Drain Current	31.5	
I_{DM}	Pulsed Drain Current ①	200	
P_D @ T_C = 25°C	Max. Power Dissipation	250	W
	Linear Derating Factor	2.0	W/°C
V_{GS}	Gate-to-Source Voltage	±20	V
E_{AS}	Single Pulse Avalanche Energy ②	283	mJ
I_{AR}	Avalanche Current ①	56	A
E_{AR}	Repetitive Avalanche Energy ①	25	mJ
dv/dt	Peak Diode Recovery dv/dt ③	5.0	V/ns
T_J T_{STG}	Operating Junction Storage Temperature Range	-55 to 150	°C
	Pckg. Mounting Surface Temp.	300 (for 5s)	
	Weight	3.3 (Typical)	g

For footnotes refer to the last page

12/21/11

Electrical Characteristics @ Tj = 25°C (Unless Otherwise Specified)

	Parameter	Min	Typ	Max	Units	Test Conditions
BV_{DSS}	Drain-to-Source Breakdown Voltage	250	—	—	V	V_{GS} = 0V, I_D = 1.0mA
$\Delta BV_{DSS}/\Delta T_J$	Temperature Coefficient of Breakdown Voltage	—	0.3	—	V/°C	Reference to 25°C, I_D = 1.0mA
$R_{DS(on)}$	Static Drain-to-Source On-State Resistance	—	—	0.028	Ω	V_{GS} = 12V, I_D = 31.5A ④
$V_{GS(th)}$	Gate Threshold Voltage	2.0	—	4.0	V	V_{DS} = V_{GS}, I_D = 1.0mA
$\Delta V_{GS(th)}/\Delta T_J$	Gate Threshold Voltage Coefficient	—	-10.1	—	mV/°C	
g_{fs}	Forward Transconductance	37	—	—	S	V_{DS} = 15V, I_{DS} = 31.5A ④
I_{DSS}	Zero Gate Voltage Drain Current	—	—	10	µA	V_{DS}= 200V ,V_{GS}=0V
		—	—	25		V_{DS} = 200V, V_{GS} = 0V, T_J = 125°C
I_{GSS}	Gate-to-Source Leakage Forward	—	—	100	nA	V_{GS} = 20V
I_{GSS}	Gate-to-Source Leakage Reverse	—	—	-100		V_{GS} = -20V
Q_g	Total Gate Charge	—	—	220	nC	V_{GS} = 12V, I_D = 50A
Q_{gs}	Gate-to-Source Charge	—	—	50		V_{DS} = 125V
Q_{gd}	Gate-to-Drain ('Miller') Charge	—	—	70		
$t_{d(on)}$	Turn-On Delay Time	—	—	35	ns	V_{DD} = 125V, I_D = 50A,
t_r	Rise Time	—	—	70		V_{GS} = 12V, R_G = 2.35Ω
$t_{d(off)}$	Turn-Off Delay Time	—	—	80		
t_f	Fall Time	—	—	15		
$L_S + L_D$	Total Inductance	—	2.8	—	nH	Measured from the center of drain pad to center of source pad
Ciss	Input Capacitance	—	6912	—	pF	V_{GS} = 0V, V_{DS} = 25V
C_{oss}	Output Capacitance	—	940	—		f = 100KHz
C_{rss}	Reverse Transfer Capacitance	—	10.8	—		
R_g	Gate Resistance	—	0.52	—	Ω	f = 1.0MHz, open drain

Source-Drain Diode Ratings and Characteristics

	Parameter	Min	Typ	Max	Units	Test Conditions
I_S	Continuous Source Current (Body Diode)	—	—	50	A	
I_{SM}	Pulse Source Current (Body Diode) ①	—	—	200		
V_{SD}	Diode Forward Voltage	—	—	1.2	V	T_j = 25°C, I_S = 50A, V_{GS} = 0V ④
t_{rr}	Reverse Recovery Time	—	—	700	ns	T_j = 25°C, I_F = 50A, di/dt ≤ 100A/µs
Q_{RR}	Reverse Recovery Charge	—	—	15	µC	V_{DD} ≤ 25V ④
t_{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by L_S + L_D.				

Thermal Resistance

	Parameter	Min	Typ	Max	Units	Test Conditions
R_{thJC}	Junction-to-Case	—	—	0.5	°C/W	

Note: Corresponding Spice and Saber models are available on International Rectifier Web site.

For footnotes refer to the last page

International Rectifier Radiation Hardened MOSFETs are tested to verify their radiation hardness capability. The hardness assurance program at International Rectifier is comprised of two radiation environments. Every manufacturing lot is tested for total ionizing dose (per notes 5 and 6) using the TO-3 package. Both pre- and post-irradiation performance are tested and specified using the same drive circuitry and test conditions in order to provide a direct comparison.

Table 1. Electrical Characteristics @ Tj = 25°C, Post Total Dose Irradiation ⑤⑥

	Parameter	Upto 300K Rads (Si)[1]		Units	Test Conditions
		Min	Max		
BV_{DSS}	Drain-to-Source Breakdown Voltage	250	—	V	$V_{GS} = 0V$, $I_D = 1.0mA$
$V_{GS(th)}$	Gate Threshold Voltage	2.0	4.0		$V_{GS} = V_{DS}$, $I_D = 1.0mA$
I_{GSS}	Gate-to-Source Leakage Forward	—	100	nA	$V_{GS} = 20V$
I_{GSS}	Gate-to-Source Leakage Reverse	—	-100		$V_{GS} = -20V$
I_{DSS}	Zero Gate Voltage Drain Current	—	10	µA	$V_{DS}= 160V$, $V_{GS}= 0V$
$R_{DS(on)}$	Static Drain-to-Source ④ On-State Resistance (TO-3)	—	0.041	Ω	$V_{GS} = 12V$, $I_D = 31.5A$
$R_{DS(on)}$	Static Drain-to-Source On-state ④ Resistance (SMD-2)	—	0.040	Ω	$V_{GS} = 12V$, $I_D = 31.5A$
V_{SD}	Diode Forward Voltage④	—	1.2	V	$V_{GS} = 0V$, $I_D = 50A$

1. Part numbers IRHNA67264, IRHNA63264

International Rectifier radiation hardened MOSFETs have been characterized in heavy ion environment for Single Event Effects (SEE). Single Event Effects characterization is illustrated in Fig. a and Table 2.

Table 2. Typical Single Event Effect Safe Operating Area

LET (MeV/(mg/cm^2))	Energy (MeV)	Range (µm)	VDS (V) @VGS= 0V	@VGS= -5V	@VGS= -10V	@VGS= -15V	@VGS= -20V
44 ± 5%	1350 ± 5%	125 ± 10%	250	250	250	250	40
61 ± 5%	825 ± 5%	66 ± 7.5%	250	250	250	50	-
90 ± 5%	1470 ± 5%	80 ± 5%	75	75	-	-	-

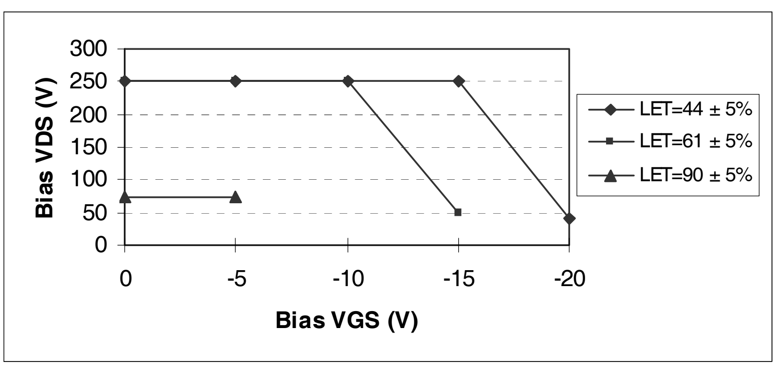


Fig a. Typical Single Event Effect, Safe Operating Area

For footnotes refer to the last page

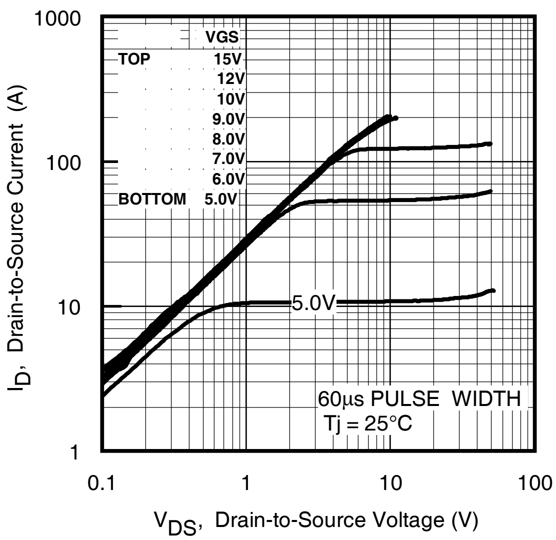


Fig 1. Typical Output Characteristics

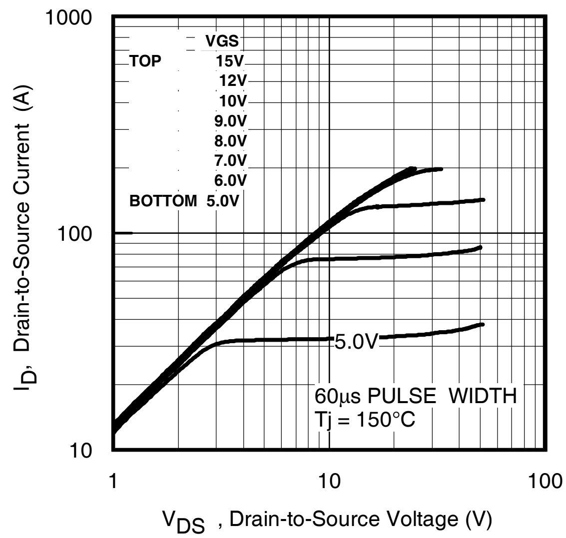


Fig 2. Typical Output Characteristics

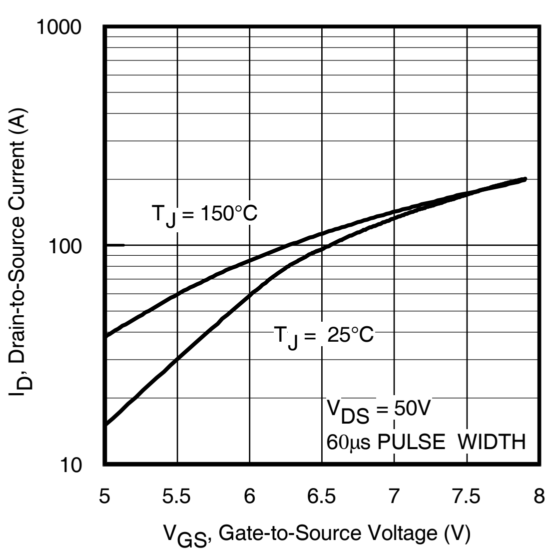


Fig 3. Typical Transfer Characteristics

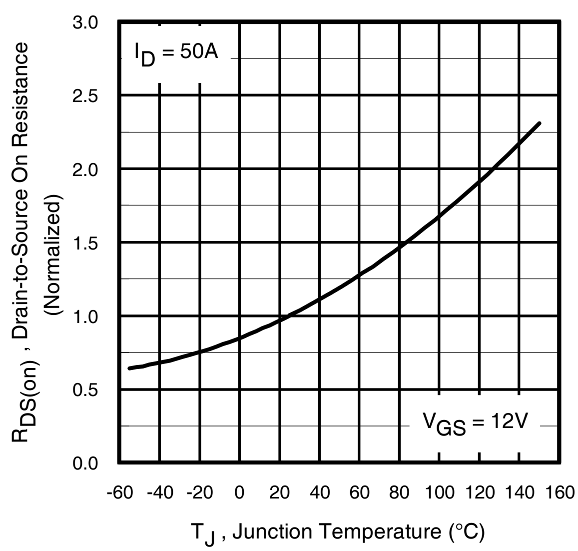


Fig 4. Normalized On-Resistance Vs. Temperature

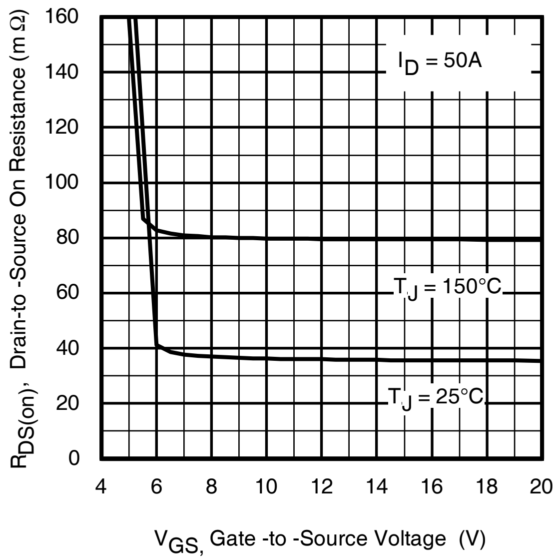


Fig 5. Typical On-Resistance Vs Gate Voltage

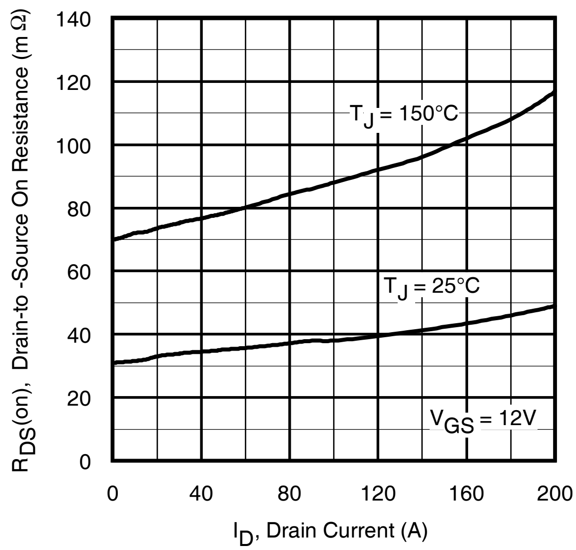


Fig 6. Typical On-Resistance Vs Drain Current

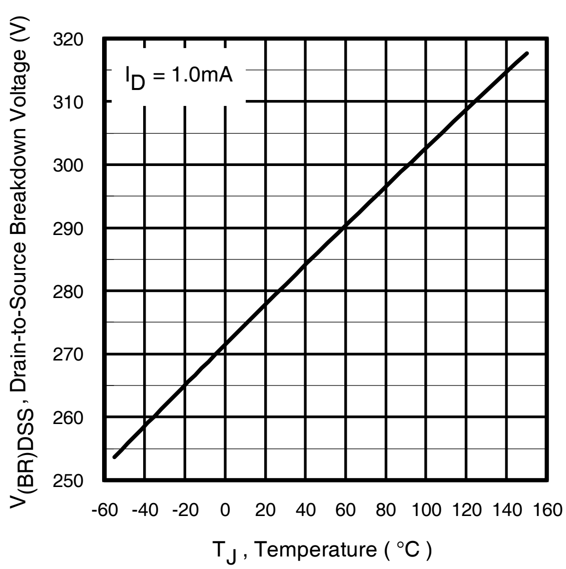


Fig 7. Typical Drain-to-Source Breakdown Voltage Vs Temperature

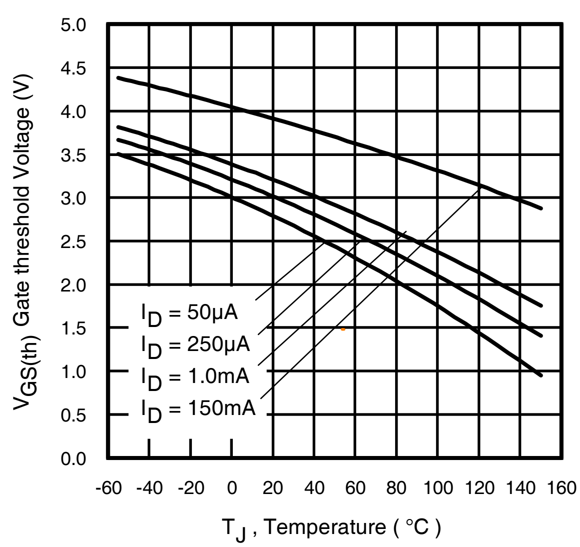


Fig 8. Typical Threshold Voltage Vs Temperature

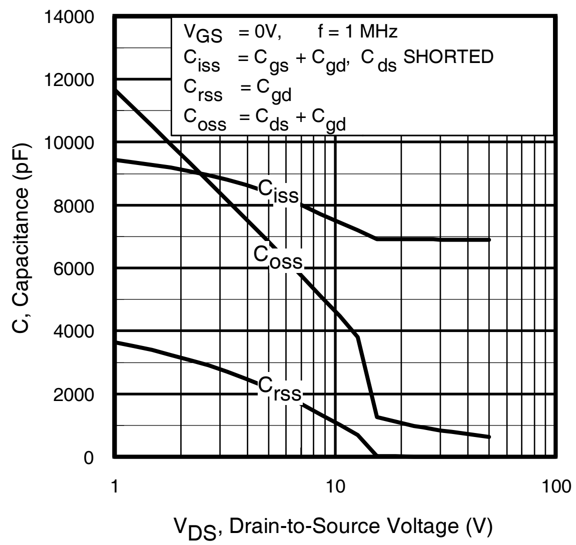


Fig 9. Typical Capacitance Vs. Drain-to-Source Voltage

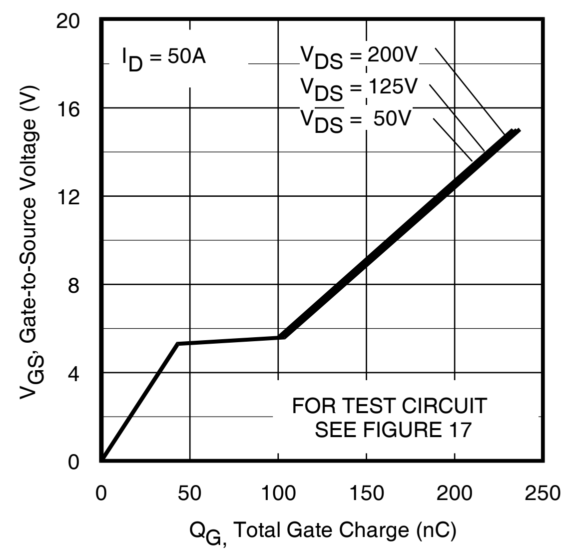


Fig 10. Typical Gate Charge Vs. Gate-to-Source Voltage

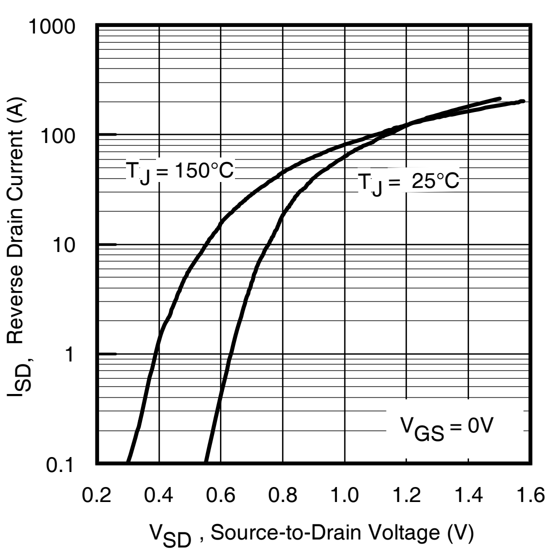


Fig 11. Typical Source-to-Drain Diode Forward Voltage

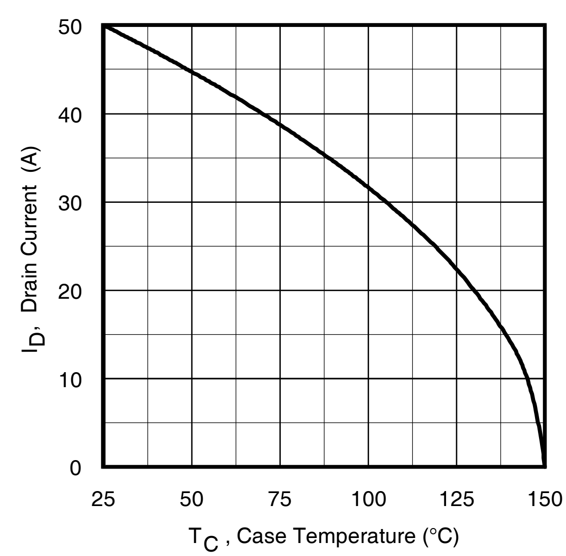


Fig 12. Maximum Drain Current Vs. Case Temperature

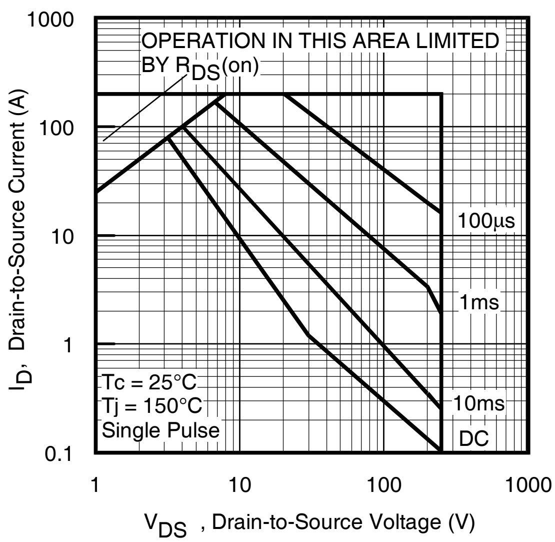


Fig 13. Maximum Safe Operating Area

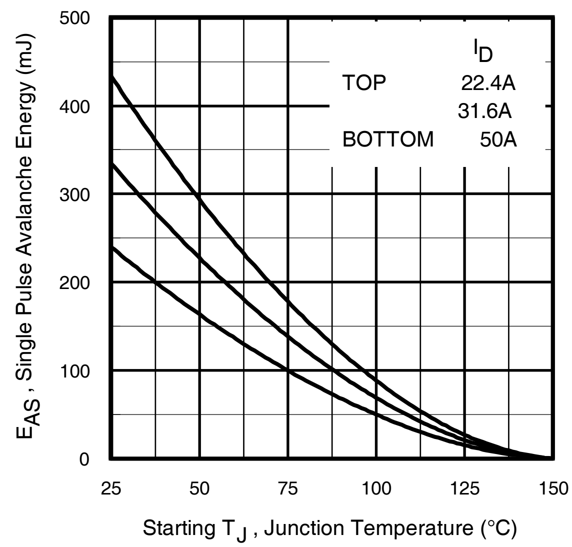


Fig 14. Maximum Avalanche Energy Vs. Drain Current

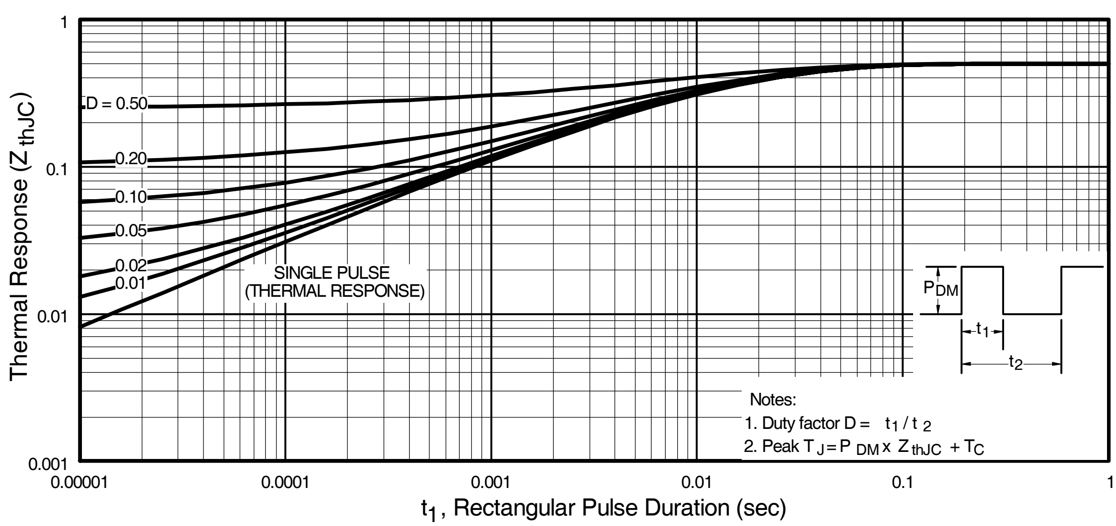


Fig 15. Maximum Effective Transient Thermal Impedance, Junction-to-Case

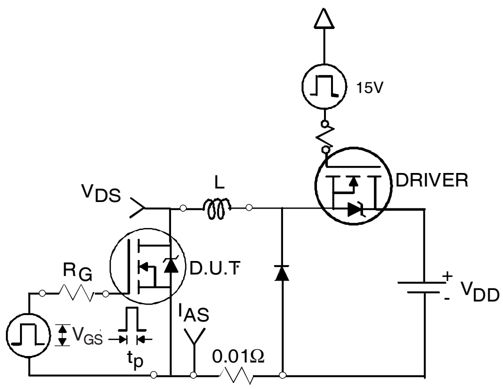


Fig 16a. Unclamped Inductive Test Circuit

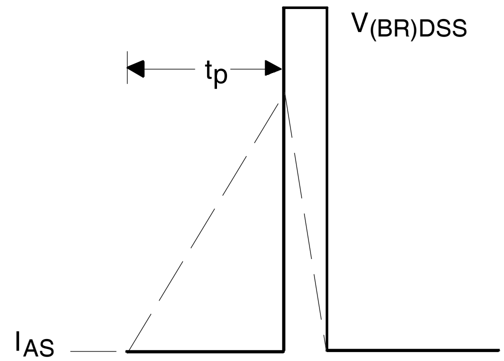


Fig 16b. Unclamped Inductive Waveforms

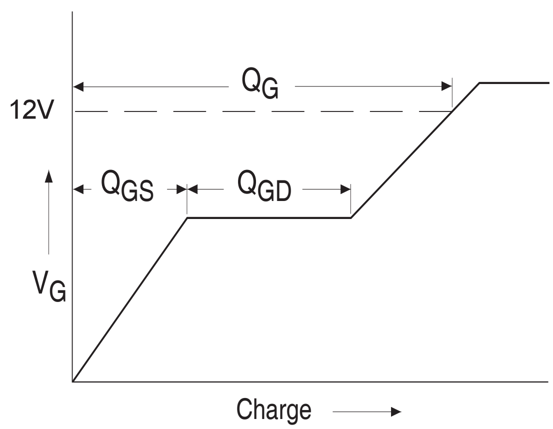


Fig 17a. Basic Gate Charge Waveform

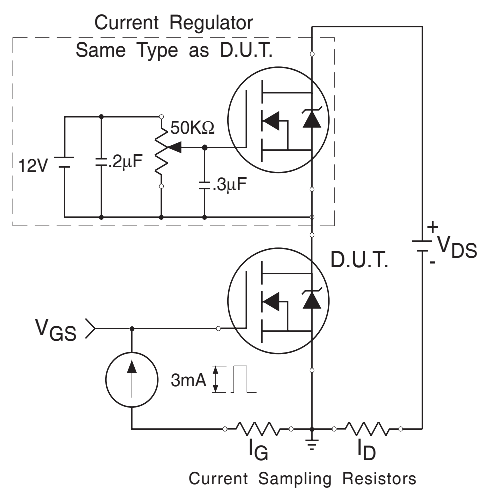


Fig 17b. Gate Charge Test Circuit

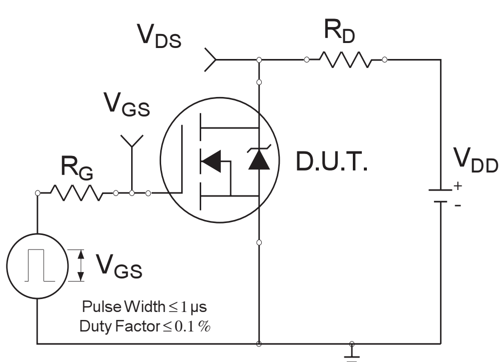


Fig 18a. Switching Time Test Circuit

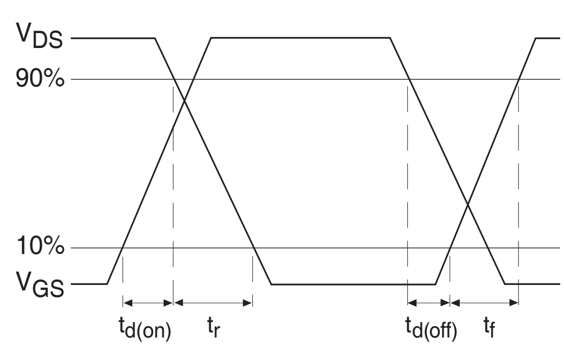
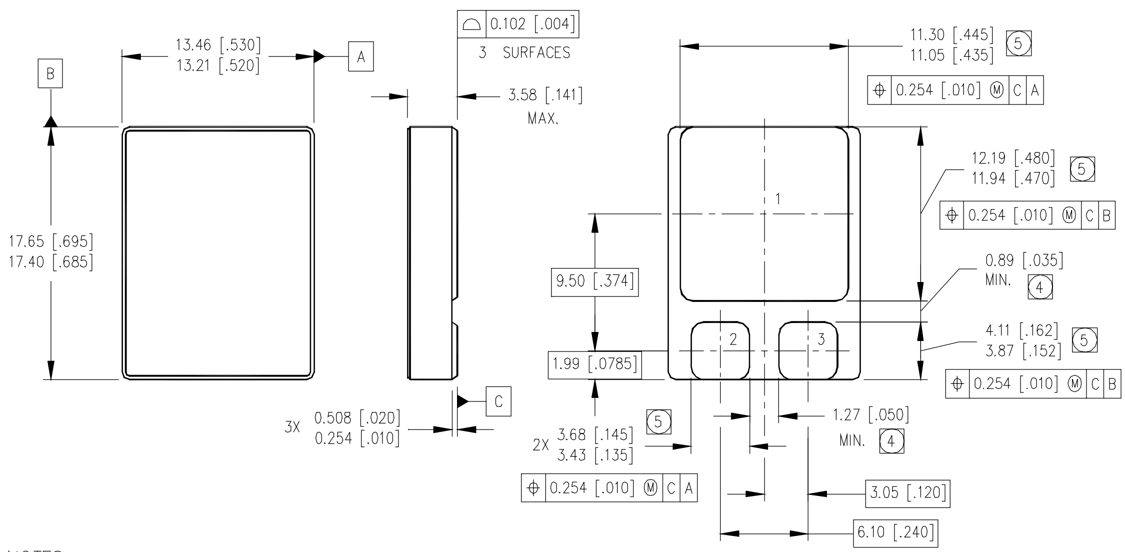


Fig 18b. Switching Time Waveforms

Footnotes:

① Repetitive Rating; Pulse width limited by maximum junction temperature.
② V_{DD} = 50V, starting T_J = 25°C, L= 0.19mH Peak I_L = 50A, V_{GS} = 12V
③ I_{SD} ≤ 50A, di/dt ≤ 900A/µs, V_{DD} ≤ 250V, T_J ≤ 150°C
④ Pulse width ≤ 300 µs; Duty Cycle ≤ 2%
⑤ **Total Dose Irradiation with V_{GS} Bias.** 12 volt V_{GS} applied and V_{DS} = 0 during irradiation per MIL-STD-750, method 1019, condition A.
⑥ **Total Dose Irradiation with V_{DS} Bias.** 200 volt V_{DS} applied and V_{GS} = 0 during irradiation per MIL-STD-750, method 1019, condition A.

Case Outline and Dimensions — SMD-2



NOTES:
1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
4 DIMENSION INCLUDES METALLIZATION FLASH.
5 DIMENSION DOES NOT INCLUDE METALLIZATION FLASH.

PAD ASSIGNMENTS
1 = DRAIN
2 = GATE
3 = SOURCE

International
IOR Rectifier

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